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 TI Lead-free **tin-base solder** pastes for chip bonding  
 IN Kato, Rikiya; Munakata, Osamu; Toyota, Yoshitaka  
 PA Senju Metal Industry Co., Ltd., Japan  
 SO Jpn. Kokai Tokkyo Koho, 7 pp.  
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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2001058286	A2	20010306	JP 1999-234345	19990820
AB	<p>The <b>Sn-base solder</b> pastes contain 0.2-1.0 wt.% <b>Ag</b>. The pastes may also contain Sb and/or <b>Cu</b> at .ltoreq.1.0 wt.% or Ni, Co, Fe, Mn, Cr, and/or Mo at .ltoreq.0.3 wt.% as strengthening elements, Bi, In, and/or Zn at 0.5-3.0 wt.% as m.p.-lowering elements, and/or <b>P</b>, Ga, and/or Ge at .ltoreq.0.2 wt.% as antioxidant elements. The solder pastes prevent rising of electronic chips during bonding them onto printed circuit boards, etc.</p>				